

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Teck Kheng Lee

Serial No.: 10/829,647

Filed: April 22, 2004

For: METHODS FOR ASSEMBLY AND
PACKAGING OF FLIP CHIP
CONFIGURED DICE WITH INTERPOSER

Confirmation No.: 6967

Examiner: P. Perkins

Group Art Unit: 2822

Attorney Docket No.: 2269-4974.1US
(2000-0693.01/US)

Notice of Allowance Mailed:

March 19, 2008

VIA ELECTRONIC FILING
June 13, 2008

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

Amendments to the specification begin on page 3 of this paper;

Amendments to the Abstract appear on page 23 of this paper;

Amendments to the claims are set forth in the listing of the claims that begins on page 24 of this paper;

Corrections to the drawings are summarized on page 27 of this paper, with replacement sheets and annotated sheets showing the corrections enclosed herewith; and

Remarks start at page 28 of this paper.